SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

ABSTRACT

Semiconductor device (3) comprises semiconductor chip (11), Au ball bumps (21) formed on pad electrodes (12) with a stud bump method, and thermoplastic adhesive layer (22) provided on the surface of semiconductor chip (11) on which pad electrodes (12) are formed, in which the tops of Au ball bumps (21) project from the surface of adhesive layer (22). Reliable bonding can be realised by forming the bumps for electrical connection and the adhesive resin having an adhesion function on the semiconductor chip. In addition, the present invention provides a method of bonding a copper foil to a semiconductor wafer to form a wiring pattern, a multi chip module in which electrical connection is established by bumps bonded to each other through an adhesive layer, and the like.

Fig. 4